

SURFACE MOUNT SUPER FAST RECTIFIER

Features

- ◆ Glass passivated device
- ◆ Ideal for surface mounted applications
- ◆ Low reverse leakage
- ◆ Metallurgically bonded construction
- ◆ High temperature soldering guaranteed:
250°C/10 seconds, 0.375" (9.5mm) lead length,
5 lbs. (2.3kg) tension

Mechanical Data

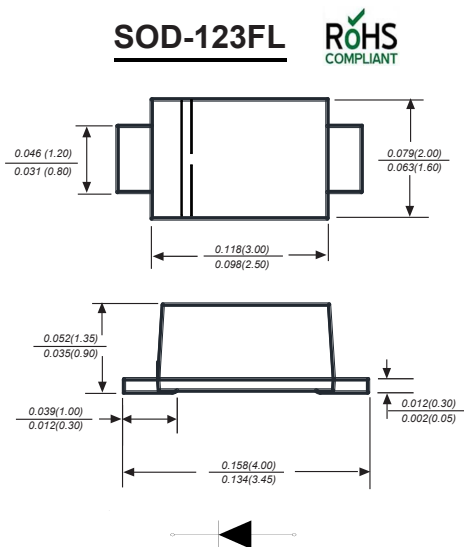
Case : JEDEC SOD-123FL molded plastic body

Terminals : Solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0007 ounce, 0.02 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	ES2AW	ES2BW	ES2CW	ES2DW	ES2EW	ES2GW	ES2JW	UNITS
Marking Code		2E1	2E2	2E3	2E4	2E5	2E6	2E8	
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V _{RMS}	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	V _{DC}	50	100	150	200	300	400	600	V
Maximum average forward rectified current at Ta=65°C	I _{AV}	2.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed onrated load (JEDEC Method)	I _{FSM}	50							A
Maximum instantaneous forward voltage at 2.0A	V _F	0.95				1.25		1.7	V
Maximum DC reverse current TA=25°C at rated DCblocking voltage TA=125°C	I _R	5 100							μA
Typical junction capacitance (NOTE 1)	C _J	25							pF
Maximum Reverse Recovery Time (NOTE 2)	t _{rr}	35							ns
Typical thermal resistance (NOTE 3)	R _{θJA}	90							°C/W
Operating junction temperature range	T _J	-55 to +125							°C
Storage temperature range	T _{STG}	-55 to +150							°C

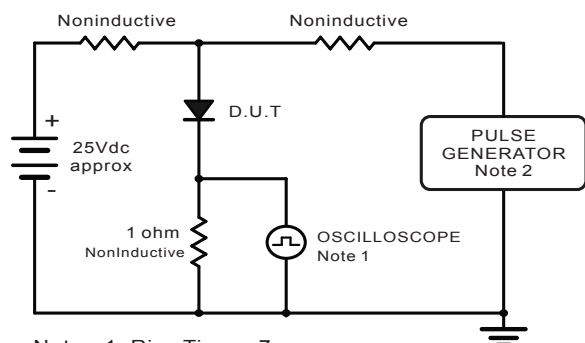
Note: 1. Measured with $I_F=0.5\text{A}$, $I_R=1\text{A}$, $I_{rr}=0.25\text{A}$.

2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

3. PCB mounted on 0.2*0.2" (5.0*5.0mm) copper pad area.

Typical Characteristics

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm, 22pF.
2. Rise Time = 10ns, max.
Source Impedance = 50 ohms.

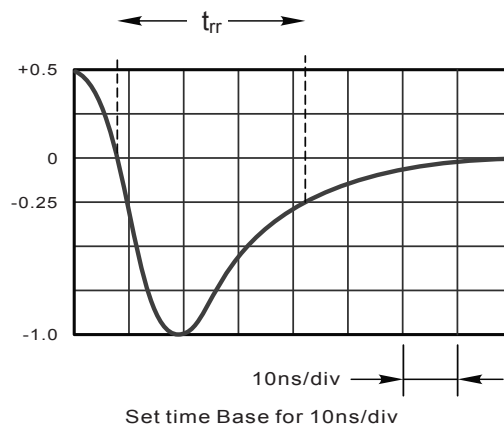


Fig.2 Maximum Average Forward Current Rating

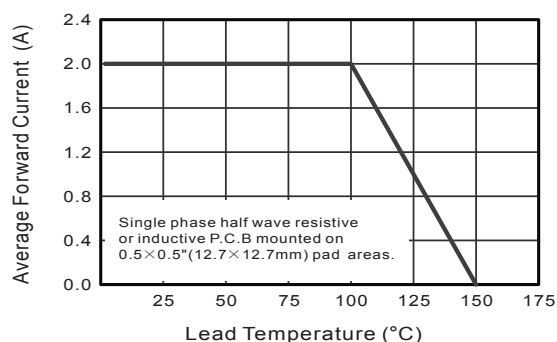


Fig.3 Typical Reverse Characteristics

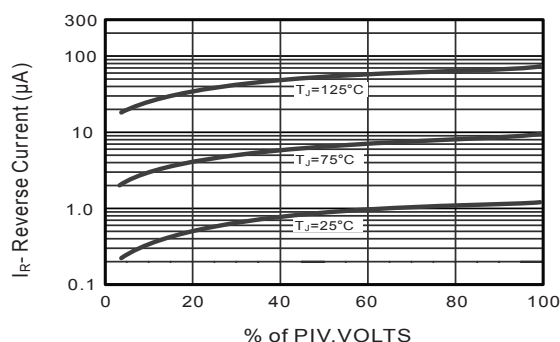


Fig.4 Typical Forward Characteristics

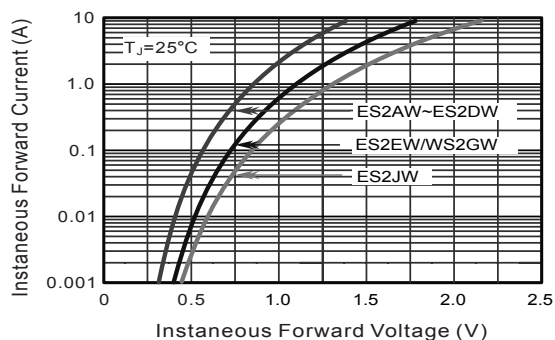


Fig.5 Typical Junction Capacitance

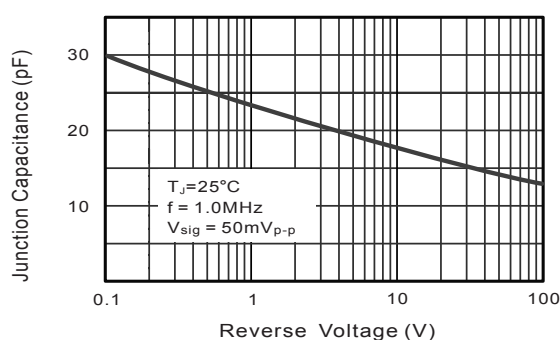
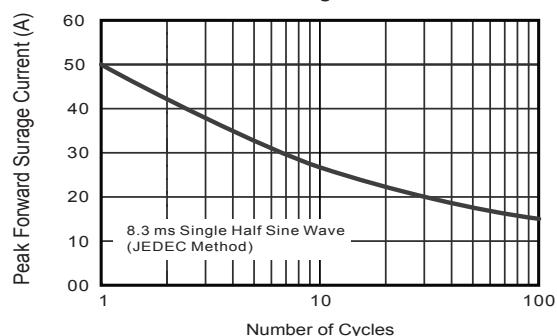
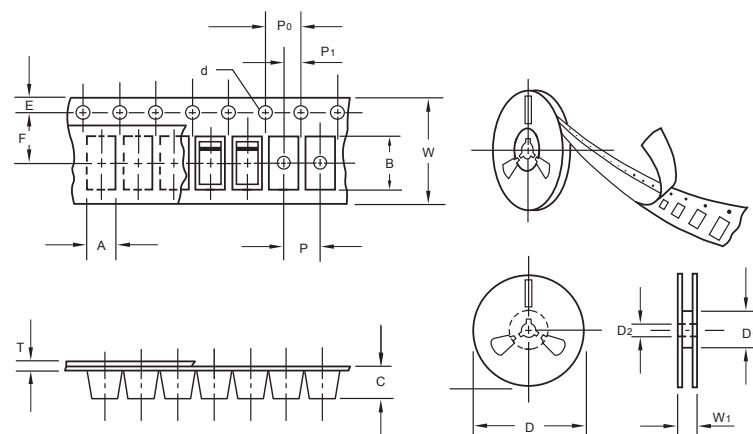


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current



The curve above is for reference only.

Packing information



unit:mm

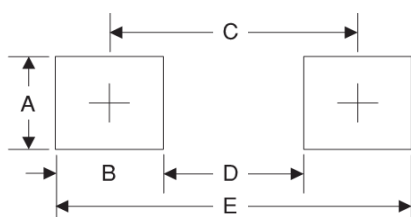
Item	Symbol	Tolerance	SOD-123FL
Carrier width	A	0.1	2.1
Carrier length	B	0.1	4.0
Carrier depth	C	0.1	1.60
Sprocket hole	d	0.05	1.55
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	50.0
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	8.15
Reel width	W1	1.0	10.5

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-123FL	7"	3,000	4.0	45,000	210*208*203	178	430*430*235	180,000	9.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.2	0.047
B	1.2	0.047
C	3.2	0.126
D	2	0.079
E	4.4	0.173